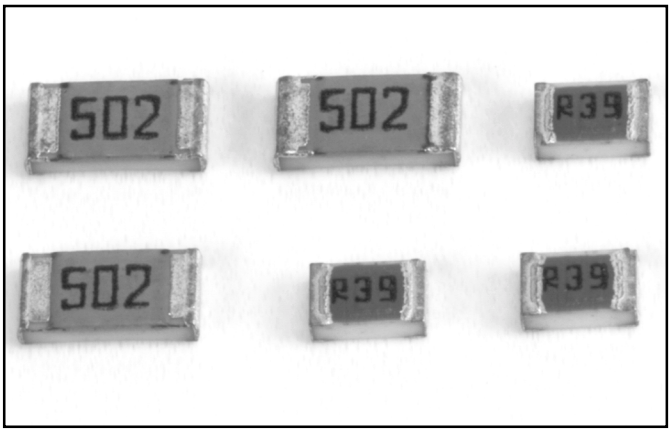

FLAT CHIP RESISTOR
NEGATIVE TEMPCO THERMISTOR

- Anti-Leaching Nickel Barrier Terminations
- 90/10 Solder Plating
- 12 Standard Resistance Values
- Suitable for Reflow & Wave Solder

STANDARD APPLICATIONS

STYLE	RESISTANCE @ 25°C (Ω)	RESISTANCE TOLERANCE	B CONSTANT (K)	B CONSTANT TOLERANCE	THERMAL DISSIPATION CONSTANT(mW)	POWER DISSIPATION (mW)	OPERATING TEMP. RANGE
2A	1.0K	K (±10%) L (±15%)	3200	±10%	2.8	5	-55°C to +125°C
	2.0K		3500				
	2.2K						
	2.4K						
	3.3K						
	4.7K						
	5.0K						
	6.8K		3800				
	10K	J (± 5%) K (±10%) L (±15%)	3500	±5%			
	10K		3800				
	15K						
	22K						
	30K						
	33K						
	47K						
	68K						
	100K						
	150K						
2B	1.0K	K (±10%) L (±15%)	3200	±10%	3.0	5	-55°C to +125°C
	2.2K		3500				
	3.3K						
	4.7K						
	6.8K		3800				
	10K	J (± 5%) K (±10%) L (±15%)		± 5%			
	22K						
	33K						
	47K						
	68K						
	100K						

ORDERING & SPECIFYING INFORMATION*

NT73	2B	T	102	L
Type	Size Code	Packaging	Nominal Resistance	Tolerance
NT73	(See Page 7) 2A: 0805 2B: 1206	(See Appendix D) T: Punched Paper	2 Significant Figures & 1 Multiplier	J: ±5% K: ±10% L: ±15%

*Please Note: KSE's Part Numbers Do Not Contain any Spaces or Hyphens.

RT/R25 RATIO VS. B CONSTANT

T (TEMP.°C)	B CONSTANT (K)				T (TEMP.°C)	B CONSTANT (K)		
	3200	3500	3800			3200	3500	3800
– 55	51.45	74.45	107.72		35	0.706	0.683	0.661
– 50	37.02	51.94	72.87		40	0.598	0.570	0.543
– 45	27.03	36.82	50.15		45	0.509	0.478	0.448
– 40	20.00	26.48	35.07		50	0.436	0.403	0.373
– 35	14.99	19.32	24.90		55	0.375	0.342	0.312
– 30	11.36	14.27	17.92		60	0.323	0.291	0.262
– 25	8.71	10.68	13.08		65	0.281	0.249	0.221
– 20	6.75	8.08	9.66		70	0.244	0.214	0.188
– 15	5.28	6.18	7.22		75	0.214	0.185	0.160
– 10	4.17	4.77	5.46		80	0.188	0.160	0.137
– 5	3.33	3.72	4.17		85	0.165	0.140	0.118
0	2.67	2.93	3.21		90	0.146	0.122	0.102
5	2.17	2.33	2.50		95	0.130	0.107	0.088
10	1.77	1.86	1.97		100	0.115	0.094	0.077
15	1.45	1.50	1.56		105	0.103	0.083	0.067
20	1.20	1.22	1.24		110	0.092	0.074	0.059
25	1.00	1.00	1.00		115	0.083	0.066	0.052
30	0.838	0.824	0.810		120	0.075	0.058	0.046
					125	0.067	0.052	0.041

NOTE: RT / R25 Ratio is the Resistance at Temperature (T) divided by the Nominal Resistance at 25°C

ENVIRONMENTAL SPECIFICATIONS

PARAMETER	MAXIMUM Δ R	TEST METHOD
High Temperature Exposure	±3.0%	80° C for 1000 hrs.
Resistance to Soldering Heat	±1.0%	MIL - R - 55342 π 4.7.7 260°C for 10 seconds
Terminal Strength-Bend	±1.0%	2mm min. Deflection in Either Direction for 10 Seconds
Moisture Resistance	±3.0%	MIL - STD - 202, Method 103 40ºC, 90 - 95%RH, 1000 Hours
Life	±3.0%	80°C, DC 5mm for 1000 hrs.
Temperature Cycling	±3.0%	30 Minutes at -55°C; 15 Minutes at +25°C. 30 Minutes at + 125°C, 15 Minutes at 25°C, 50 Cycles
	LIMITS	
Dielectric Withstanding Voltage 0805 1206	 400V 400V	 1 minute maximum MIL - STD - 202, Method 301
Insulation Resistance	10,000 Meg Ohm Min	

**RCWV = Rated Continuous Working Voltage